

ABSTRACT OF THE DISCLOSURE

There is provided a high performance onboard semiconductor device with low manufacturing costs and low repair costs. The onboard semiconductor device includes a power chip substrate on which a power chip is mounted, a control substrate provided with an electrical part in relation to the power chip, and an outer enclosing case in which the power chip substrate and the control substrate are contained, and is characterized in that the control substrate and the outer enclosing case are removably fixed to each other.